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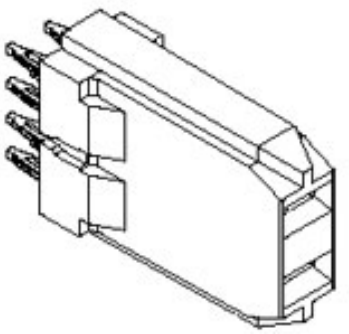
Part Number: 0740296000
Status: Active
Overview: vhdm
Description: 2.00mm (.079") Pitch VHDM® Board-to-Board Backplane Receptacle Power Module, Vertical, 6-Row, 2 Circuits, Gold (Au) Selective 0.76µm (30µ")



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Packaging Specification (PDF)
Product Specification PS-74031-999 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

UL	E29179

General

Product Family	Backplane Connectors
Series	74029
Application	Backplane
Application Tooling Documents	Tooling Manual
Comments	Backplane Receptacle Module, Power
Component Type	Power Receptacle
Overview	vhdm
Product Name	VHDM®
Style	N/A

Physical

Circuits (Loaded)	2
Circuits (maximum)	2
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Number of Columns	N/A
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.110 In
PC Tail Length (mm)	2.80 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.070 In
PCB Thickness Recommended (mm)	1.80 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.157 In
Pitch - Term. Interface (mm)	4.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75

EU RoHS RoHS Compliant by Exemption
China RoHS 50
REACH SVHC Contains SVHC: No
Halogen-Free Status Halogen-Free

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
74029Series

Mates With
74026 VHDM® Board-to-Board Daughtercard Receptacle

Application Tooling | **FAQ**

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
VHDM® Backplane 6 and 8 Row Power Module Insertion Tool	0622020211

Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.375
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

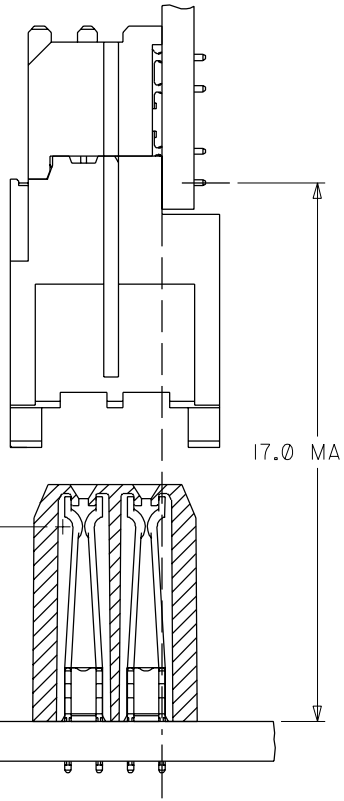
Current - Maximum per Contact	10A
Data Rate	2.5 Gbps
Real Signals (per 25mm)	72
Shielded	No
Voltage - Maximum	250V

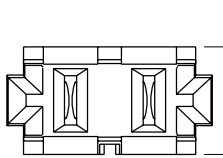
Material Info

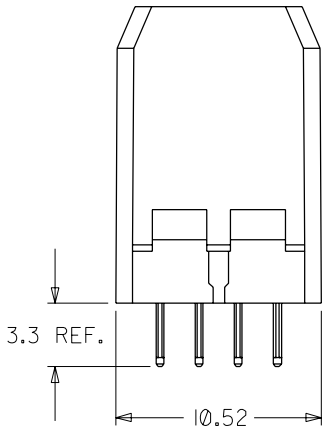
Reference - Drawing Numbers

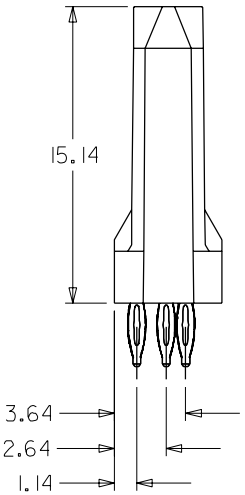
Packaging Specification	PK-70873-0876
Product Specification	PS-74031-999
Sales Drawing	SD-74029-006, SD-74029-011

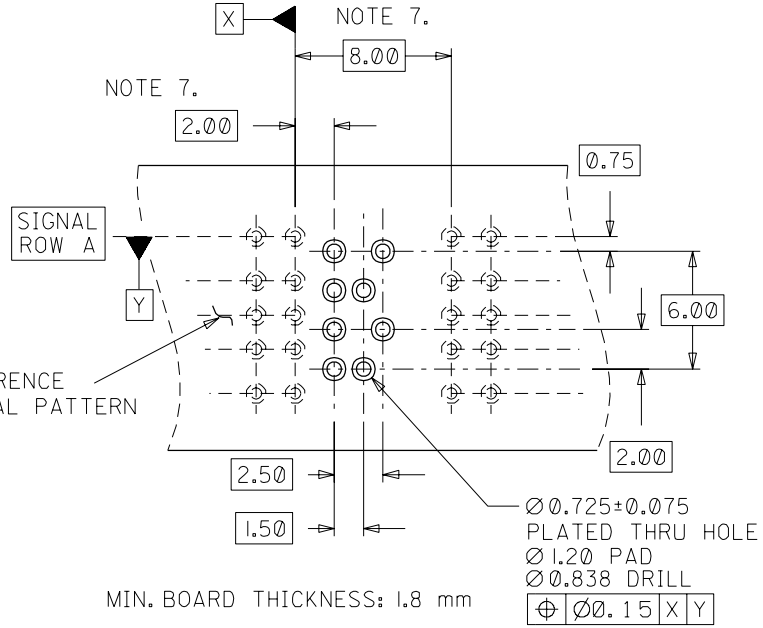
ASSEMBLY #	CONTACT PLATING
74029-6000	SEE NOTE 2.
74029-6050	SEE NOTE 3.

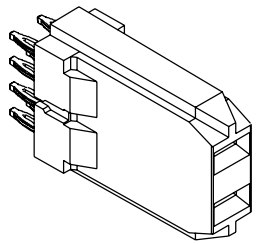












NOTES:
1. MATERIALS: HOUSING - GLASS FILLED LIQUID CRYSTAL POLYMER, UL 94V-0, BLACK; TERMINAL - COPPER ALLOY.
2. FINISH: SELECT GOLD IN CONTACT AREA, 30 microINCH THICK; TIN/LEAD IN COMPLIANT AREA.
3. FINISH: SELECT GOLD IN CONTACT AREA, 50 microINCH THICK; TIN/LEAD IN COMPLIANT AREA.
4. USE 6.0 mm NOMINAL FOR BACKPLANE LAYOUT.
5. DIMENSION IS MEASURED FROM BOTTOM OF HOUSING.
6. PACKED PER PK-70873-0876.
7. THIS DIMENSION TO BE MULTIPLE OF 2.00 mm AS REQUIRED.

REV	DESCRIPTION	EC NO.	DRWN	CHK	APPR	DATE
A	INITIAL RELEASE	UDT200 I-0940	ELO	GORSKI	BIXLER	01/05/02 01/05/03 01/05/07

QUALITY SYMBOLS
MAJOR ▼ = Ø
CRITICAL (C) = Ø

GENERAL TOLERANCES: (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±Ø.	±.
3 PLACES	±Ø.	±.
2 PLACES	±Ø.	±.
1 PLACE	±Ø.	±.
ANGULAR: ±	°	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE 4 : 1
DESIGN UNITS ☒mm ☐INCH
THIRD ANGLE PROJECTION
DIMENSIONS: ☐mm/INCH ☐INCH/mm ☒mm ONLY
SHT REV
REVISE ON CAD ONLY

DRAWN BY & DATE: ELO 01/50/02
CHECKED BY & DATE: GORSKI 01/05/03
APPROVED BY & DATE: BIXLER 01/05/07
CAD FILENAME: SD-74029-006.S01

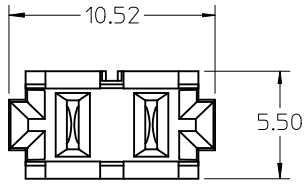
TITLE: HSD POWER 5 ROW BACKPLANE SALES ASSEMBLY

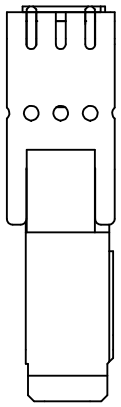
molex MOLEX INCORPORATED

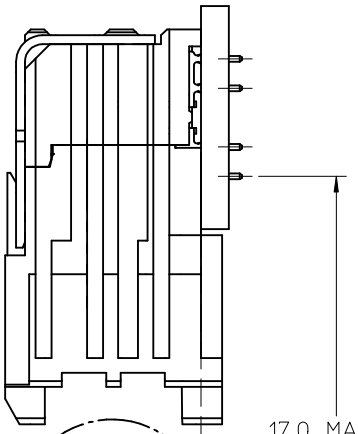
MATERIAL NO.: SEE CHART
DRAWING NO.: SD-74029-006
SHEET NO.: 1 OF 1
SIZE: B

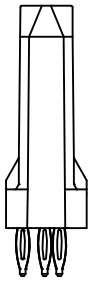
NOTES:

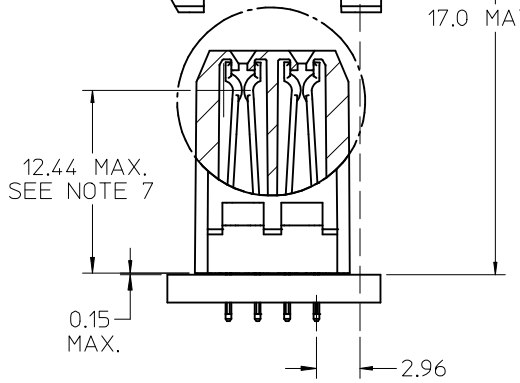
1. MATERIALS:
   HOUSING - LIQUID CRYSTAL POLYMER (LCP),
   UL94 V-0, COLOR: BLACK.
   TERMINAL - COPPER ALLOY
2. FINISH: 30 μ IN MIN. GOLD ON MATING SURFACE;
   TIN/LEAD ON TAILS; NICKEL UNDERPLATE.
3. FINISH: 50 μ IN MIN. GOLD ON MATING SURFACE;
   TIN/LEAD ON TAILS; NICKEL UNDERPLATE.
4. THIS PART CONFORMS TO PRODUCT SPECIFICATION
   PS-74031-999.
5. SINGLE ROW ASSEMBLY PACKED PER PK-70873-0876.
6. MATES WITH 74026 SERIES DAUGHTERCARD POWER ASSEMBLY.
7. MATING INTERFACE MEASURED FROM BOTTOM OF HOUSING.

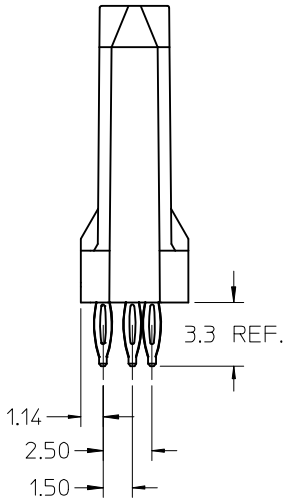


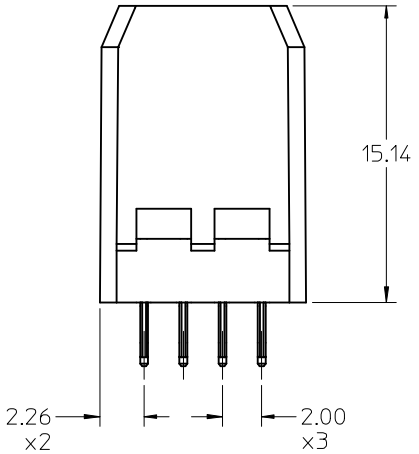












MOLEX P/N	GOLD THICKNESS
74029-6000	30uin
74029-6050	50uin

SINGLE ROW ASSEMBLY

ADD TOLERANCE
EC NO: UCP2009-3005 DRWN:BSMART 2009/06/15 CH'KD:SDANNELL 2009/06/16 APPR:SMILLER 2009/06/16
DESCRIPTION
REV D

QUALITY SYMBOLS
▼ = 0
▽ = 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

SCALE 4:1
DESIGN UNITS METRIC
THIRD ANGLE PROJECTION
REVISE ON CAD ONLY
DIMENSION STYLE MM ONLY
DRAWN BY ELO DATE 2003/07/14
CHECKED BY STANFORD DATE 2003/07/17
APPROVED BY BIXLER DATE 2003/07/21

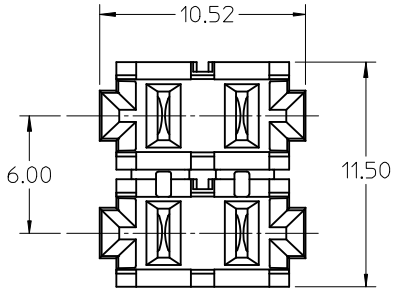
TITLE
VHDM/HSD POWER
6 ROW BACKPLANE
SALES ASSEMBLY

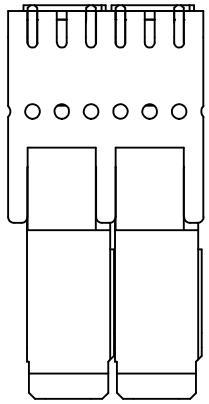
MOLEX INCORPORATED

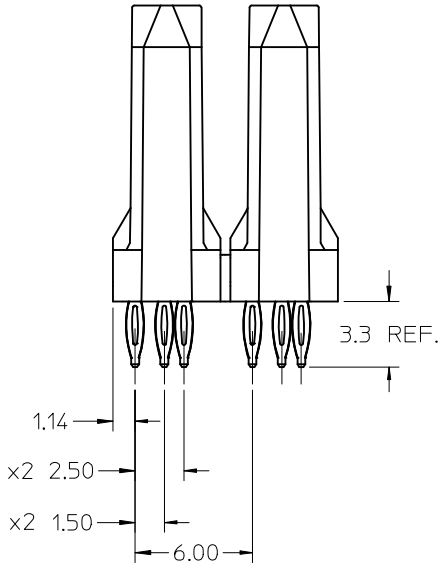
MATERIAL NO. SEE CHART
DOCUMENT NO. SD-74029-011
SHEET NO. 1 OF 3

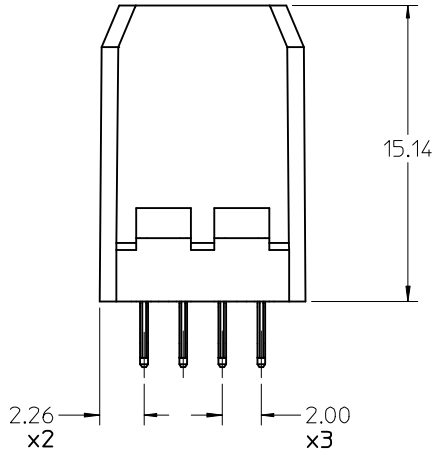
B

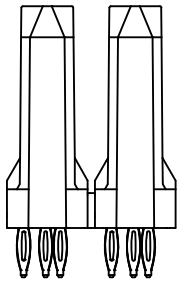
NOTES:
1. THIS DESIGN INTENDED AS OPTION TO HAVING TWO SINGLE ROW MODULES NEXT TO EACH OTHER.
2. FINISH: 30 μ IN GOLD ON MATING SURFACE; TIN/LEAD ON TAILS; NICKEL UNDERPLATE.
3. FINISH: 50 μ IN GOLD ON MATING SURFACE; TIN/LEAD ON TAILS; NICKEL UNDERPLATE.
4. DUAL ROW ASSEMBLIES PACKED PER PK-70873-545.











MOLEX P/N	CONTACT PLATING
74029-6002	SEE NOTE 2.
74029-6052	SEE NOTE 3.

DUAL ROW ASSEMBLY

SEE SHEET 1
EC NO: UCP2009-3005
DRWN:BSMART 2009/06/15
CH'KD:SDANNELL 2009/06/16
APPR: SMILLER 2009/06/16
DESCRIPTION
REV D

QUALITY SYMBOLS
▼ - 0
▽ (C) - 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ± 5 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE 4:1
DESIGN UNITS METRIC
THIRD ANGLE PROJECTION
REVISE ON CAD ONLY
DIMENSION STYLE MM ONLY
DRAWN BY ELO DATE 2003/07/14
CHECKED BY STANFORD DATE 2003/07/17
APPROVED BY BIXLER DATE 2003/07/21

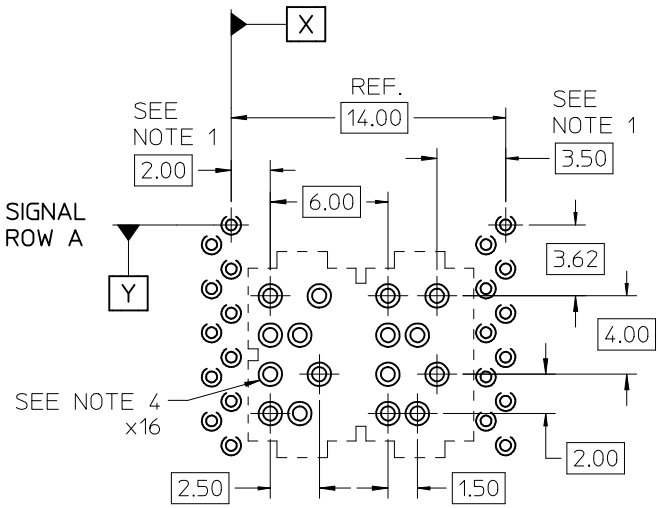
TITLE
VHDM/HSD POWER
6 ROW BACKPLANE
SALES ASSEMBLY

MOLEX INCORPORATED

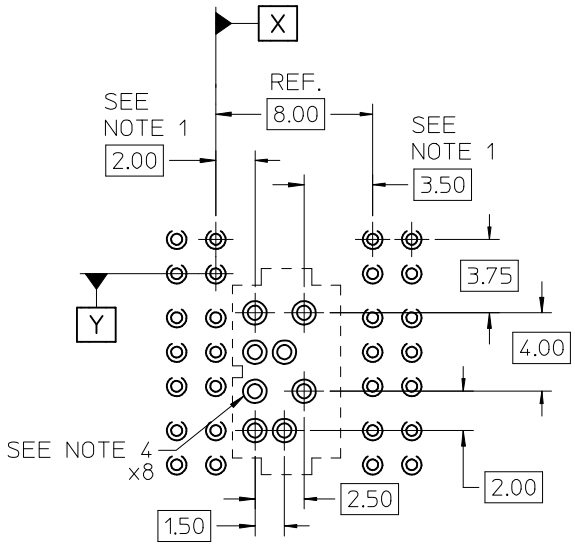
MATERIAL NO. SEE CHART
DOCUMENT NO. SD-74029-011
SHEET NO. 2 OF 3

B

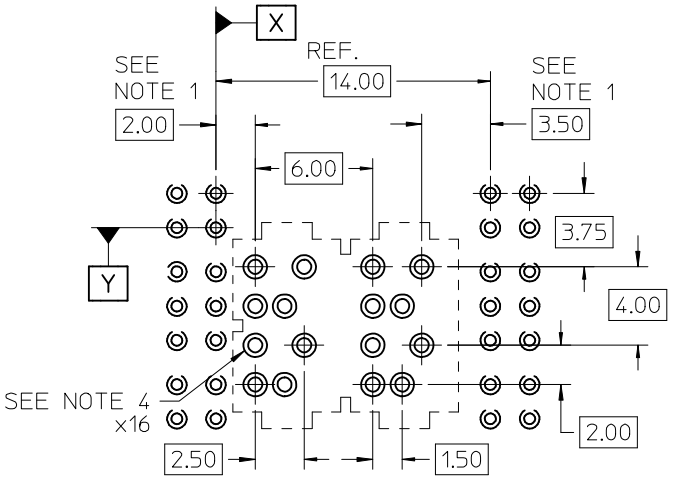
BOARD LAYOUTS: 1.8 mm MIN. BOARD THICKNESS



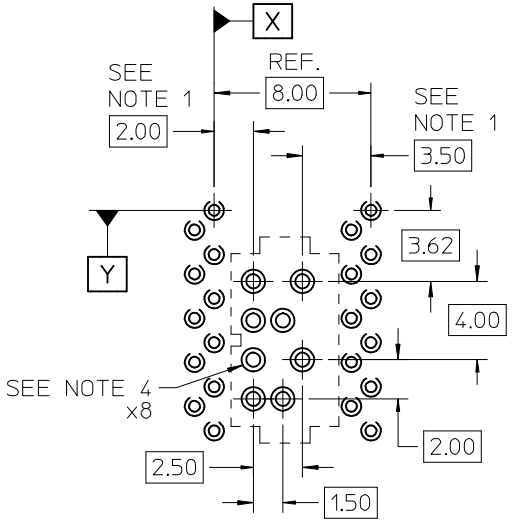
VHDM DUAL ROW POWER



VHDM-HSD SINGLE ROW POWER



VHDM-HSD DUAL ROW POWER



VHDM SINGLE ROW POWER

NOTES:
1. ADDITIONAL SPACING CAN BE ADDED IN MULTIPLES OF 2.0 mm AS REQUIRED. FOR EACH ADDITIONAL SINGLE ROW POWER, ADD 6.00 mm.
2. SIGNAL ROW A IS IN LINE WITH DATUM Y IN ALL FOUR LAYOUTS.
3. FOUR HOLES ARE USED PER POWER CONTACT.
4. EACH POWER HOLE TO BE MANUFACTURED AS FOLLOWS:
   ø0.725±0.075 PLATED THROUGH HOLE
   ø1.20 PAD
   ø0.838 DRILL
   ⌖ 0.10 X Y

SEE SHEET 1
EC NO: UCP2009-3005
DRWN:BSMART 2009/06/15
CH'KD:SDANNELL 2009/06/16
APPR:SMILLER 2009/06/16
DESCRIPTION
REV
D

QUALITY SYMBOLS
▼ - 0
▽ - 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

SCALE	4:1
DESIGN UNITS	METRIC
DIMENSION STYLE	MM ONLY
DRAWN BY	ELO
DATE	2003/07/14
CHECKED BY	STANFORD
DATE	2003/07/17
APPROVED BY	BIXLER
DATE	2003/07/21

THIRD ANGLE PROJECTION
REVISE ON CAD ONLY

TITLE
VHDM/HSD POWER
6 ROW BACKPLANE
SALES ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE SHT 1 & 2	SD-74029-011	3 OF 3

B

LifeElectronics
Живое партнерство

ООО «ЛайфЭлектроникс» **“LifeElectronics” LLC**

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- *Конкурентоспособные цены и скидки постоянным клиентам.*
- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

- *Сертификаты соответствия на поставляемую продукцию (по желанию клиента).*
- *Тестирование поставляемой продукции.*
- *Поставку компонентов, требующих военную и космическую приемку.*
- *Входной контроль качества.*
- *Наличие сертификата ISO.*

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- *Регистрацию проекта у производителя компонентов.*
- *Техническую поддержку проекта.*
- *Защиту от снятия компонента с производства.*
- *Оценку стоимости проекта по компонентам.*
- *Изготовление тестовой платы монтаж и пусконаладочные работы.*

Тел: +7 (812) 336 43 04 (многоканальный)
Email: org@lifeelectronics.ru

www.lifeelectronics.ru